

Electrophoretic Deposition for cost-reduced Solid Oxide Cell Interconnects

Martin Hilger ^{a,b}, Christian Lenser ^a, Olivier Guillon ^{a,b,c}, Norbert H. Menzler ^{a,b}

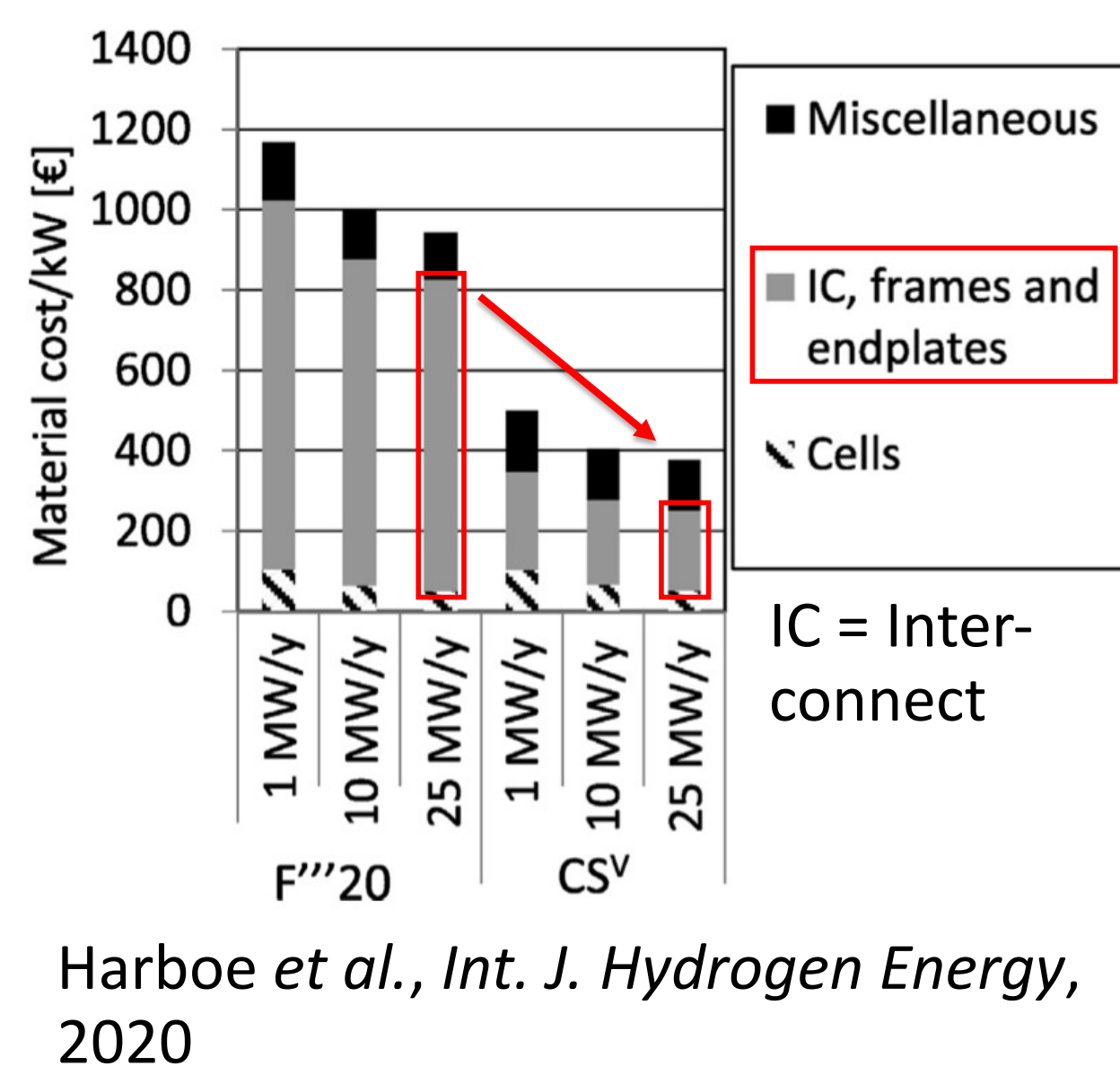
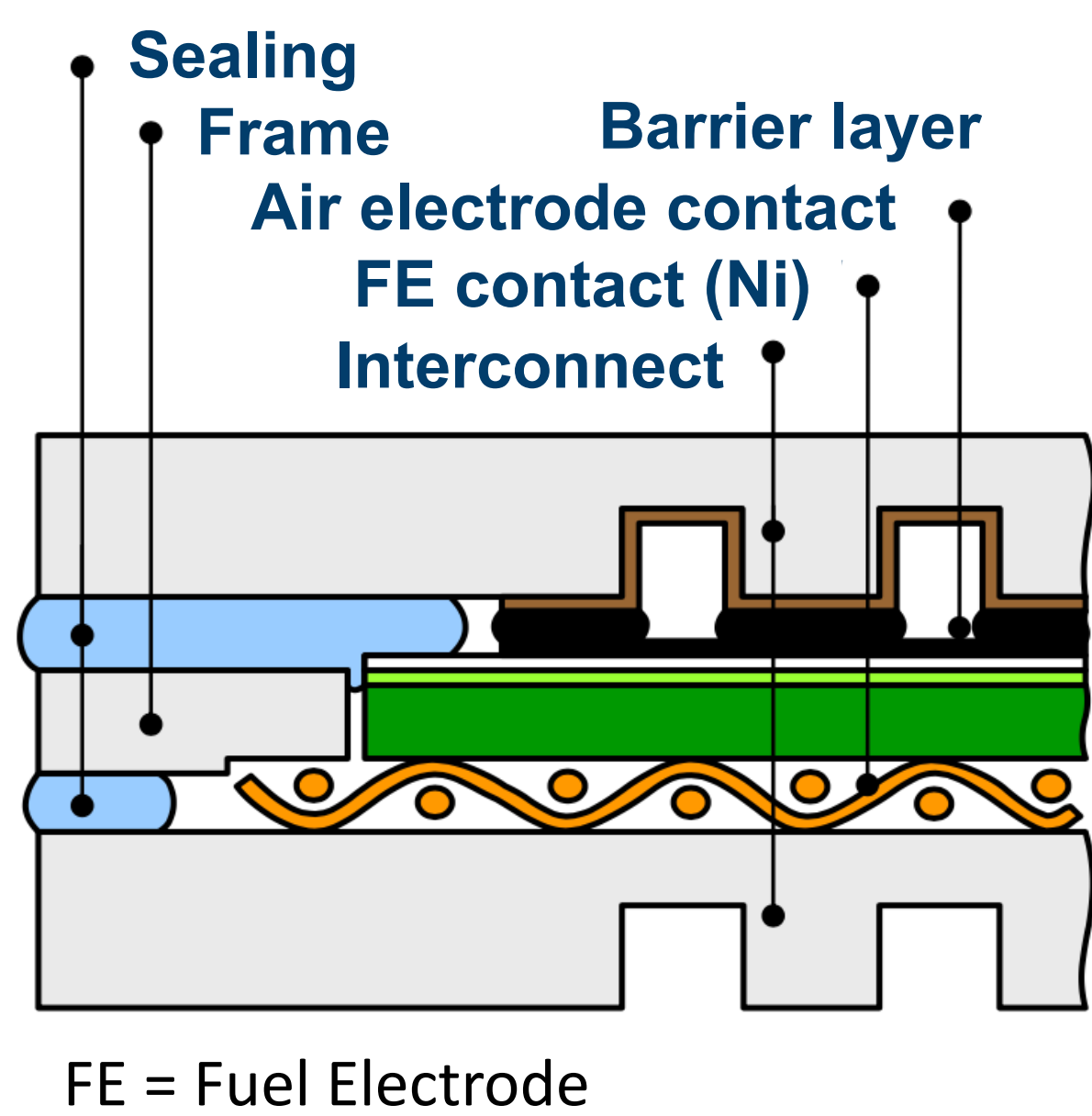
^a Forschungszentrum Jülich GmbH, IEK-1: Materials Synthesis and Processing, 52428 Jülich

^b Institute of Mineral Engineering, RWTH Aachen University, 52074 Aachen

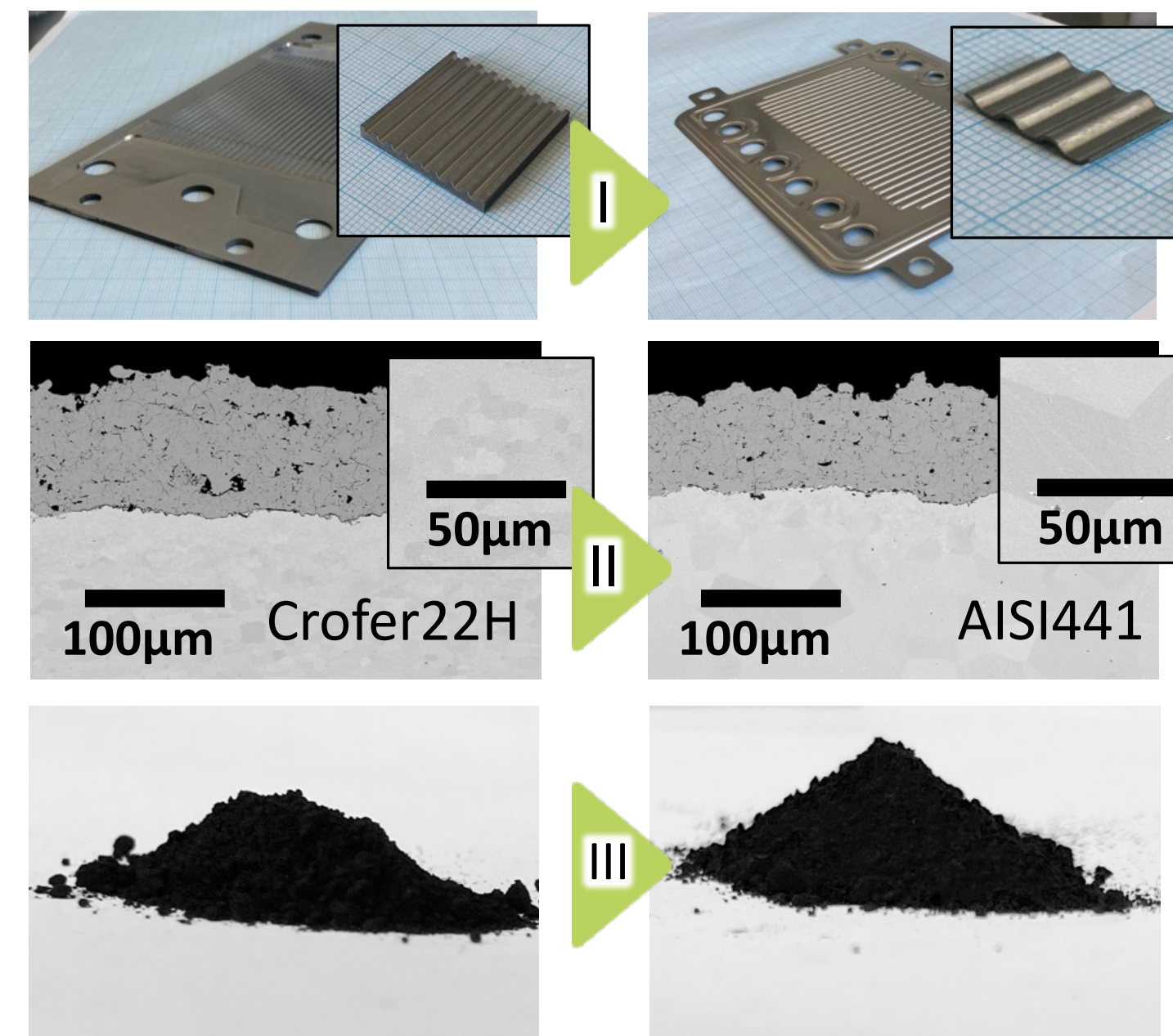
^c Jülich Aachen Research Alliance (JARA), 52062 Aachen



Introduction + Motivation



Strategies for Cost-Reduction



Thinner Interconnects

Reduce material/process costs
Coating method to be adaptable

Conventional Stainless Steels

Commercial availability
Established recycling routes

Alternative Coating Materials

Less/no Cobalt consumed
Social and ecological benefits

Materials and Processes

State-of-the art (FZ Jülich)

Interconnect

Ferritic stainless steels
→ Crofer22APU, Crofer22H

Coating

Mn-Co-based Spinel
(Mn,Co,(Fe))₃O₄

Coating method

Atmospheric Plasma Spraying

Alternatives

Interconnect

Commercial stainless steels
→ AISI430, AISI441

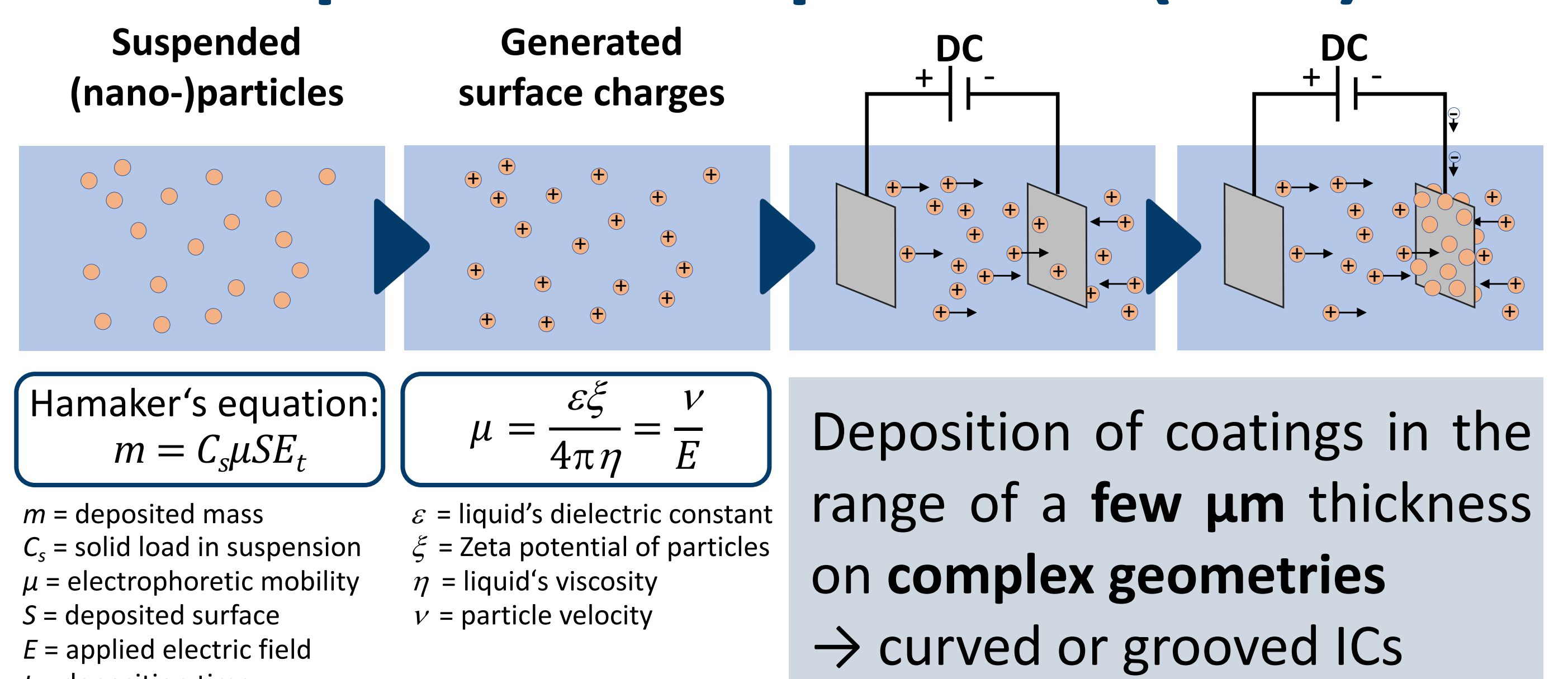
Coating

Co-free Spinel
→ (Cu,Mn,(Fe,Ni))₃O₄

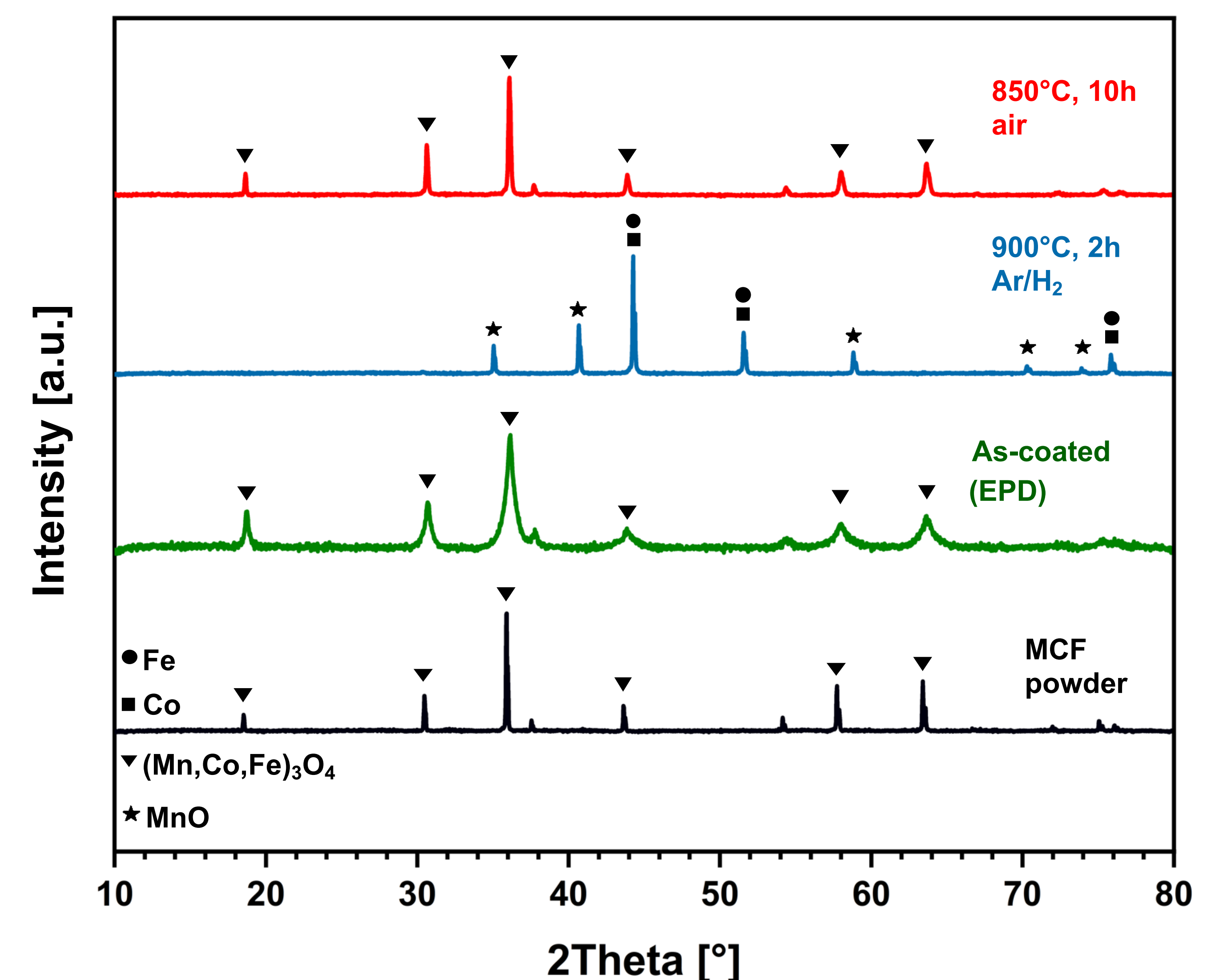
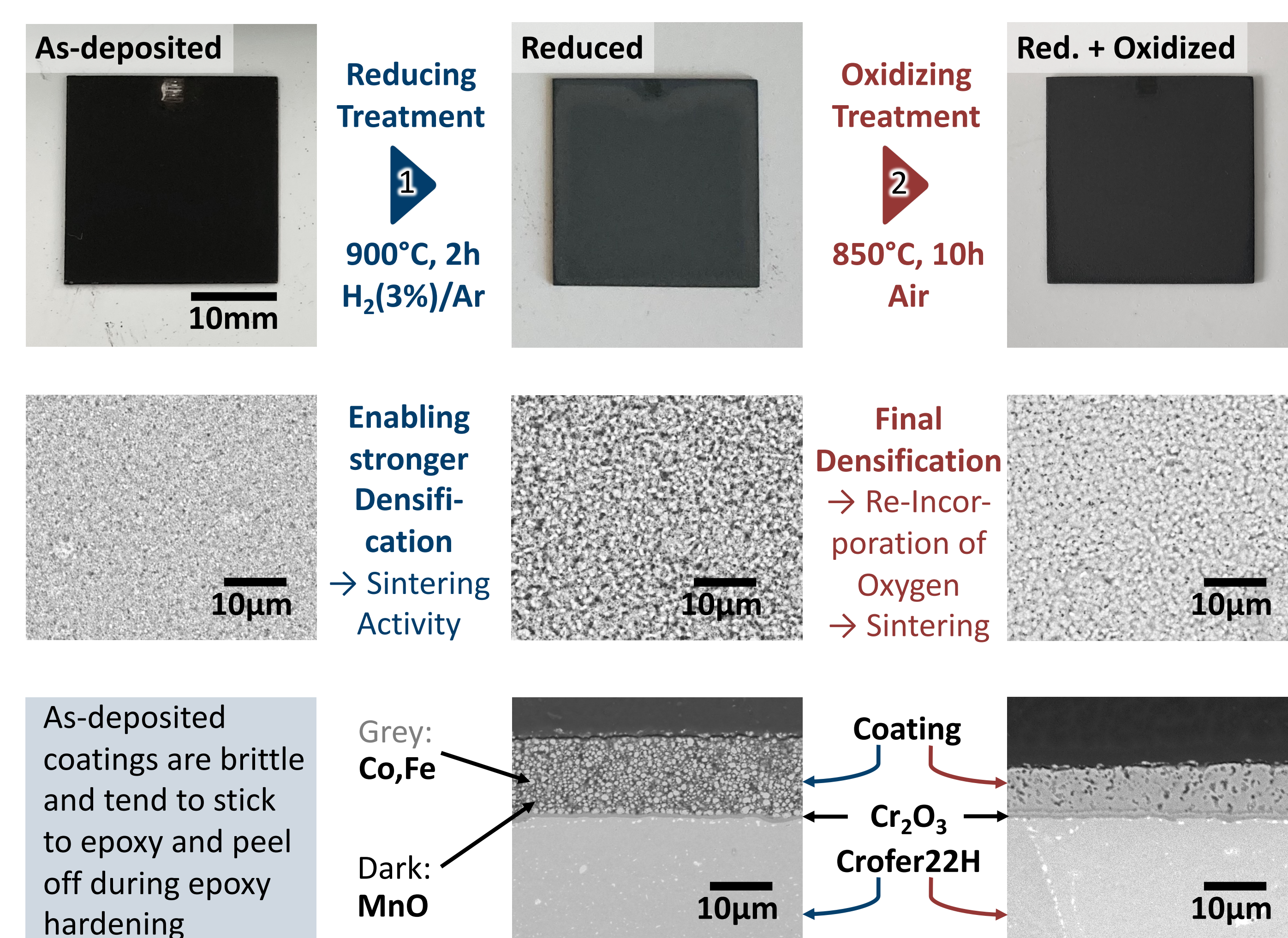
Coating method

Electrophoretic Deposition

Electrophoretic Deposition (EPD)



Thermal Processing of EPD-coatings



Conclusion

Large potential of **reducing SOC processing and material costs** lays in interconnect

EPD-Spinel-coatings display a meaningful strategy for **commercial interconnects**

Outlook

Optimization of EPD-coatings with **alternative materials** on real structures

Characterization of coatings properties at **lab-scale** and on **stack-level**

Acknowledgements

We acknowledge the financial support from the European Union's Horizon Europe research and innovation programme under grant agreement N°101058784.

